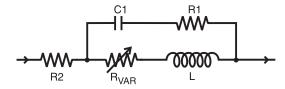
SPICE Model – 0402HL

This lumped-element (SPICE) model data simulates the frequency-dependent behavior of Coilcraft RF surface mount inductors from 1 MHz to the upper frequency limit shown in the accompanying table.

The equivalent lumped element model schematic is shown below. The element values R1, R2, C, and L are listed for each component value. The value of the frequency-dependent variable resistor R_{VAR} relates to the skin effect and is calculated from:

$$R_{VAB} = k * \sqrt{f}$$

- k is shown for each value in the accompanying table.
- f is the frequency in Hz



The data represents de-embedded measurements, as described below. Effects due to different customer circuit board traces, board materials, ground planes or interactions with other components are not included and can have a significant effect when comparing the simulation to measurements of the inductors using typical production verification instruments and fixtures.

Each model should only be analyzed at the input and output ports. Individual elements of the model are not determined by parameter measurement. The elements are determined by the overall performance of the lumped element model compared to the measurements taken of the component.

Typically, the Self-Resonant Frequency (SRF) of the component model will be higher than the measurement of the component mounted on a circuit board. The parasitic reactive elements of a circuit board or fixture will effectively lower the circuit resonant frequency, especially for very small inductance values. Since data sheet specifications are based on typical production measurements, and the SPICE models are based on de-embedded measurements as described below, the model results may be different from the data sheet specifications.

Lumped Element Modeling Method

The measurements were made over a brass ground plane with each component centered over an air gap, as illustrated in Figure 1. The gap width for each size component is given in Table 1. The test pads were 30 mil

Table 1. Test Gap

Size	Gap Width (inch/mm)				
0302	0.017 / 0.432				
0402,0403	0.017 / 0.432				
0603	0.026 / 0.660				
0805	0.040 / 1.016				
1008	0.060 / 1.524				
1206	0.080 / 2.032				
1812	0.120 / 3.048				

(50 Ohm) wide traces of tinned gold over 25 mil thick alumina, and were not included in the gap. The TRL* calibration plane is also illustrated in Figure 1.

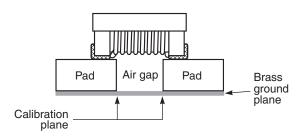


Figure 1. Test Setup

The lumped element values were determined by matching the simulation model to an average of the measurements. This method results in a model that represents as closely as possible the typical frequency-dependent behavior of the component up to a frequency just above the self-resonant frequency of the model.

The lumped element models were used to generate our 2-port S-parameters and therefore give identical results. The S-parameters are available on our web site at http://www.coilcraft.com/models.cfm.

Disclaimer

Coilcraft makes every attempt to provide accurate measurement data and software, representative of our components, in a usable format. Coilcraft, however, disclaims all warrants relating to the use of its data and software, whether expressed or implied, including without limitation any implied warranties of merchantability or fitness for a particular purpose. Coilcraft cannot and will not be liable for any special, incidental, consequential, indirect or similar damages occurring with the use of the data and/or software.



SPICE Model for Coilcraft 0402HL Chip Inductors

Part number	R1 (Ω)	R2 (Ω)	C(pF)	L(nH)	k	Upper limit (MHz)
0402HI -271	78	1.95	0.160	270	6.00E-04	1000
0.022 2						
0402HL-301	95	2.15	0.190	300	7.00E-04	1000
0402HL-331	80	2.23	0.225	330	6.00E-04	800
0402HL-361	100	2.36	0.230	360	9.00E-04	700
0402HL-391	65	2.35	0.730	390	8.00E-04	400
0402HL-471	60	2.67	1.10	470	5.00E-04	400
0402HL-511	130	3.50	0.220	510	8.00E-04	700
0402HL-561	130	3.70	0.185	560	7.00E-04	900
0402HL-601	150	3.78	0.172	600	4.00E-06	1000
0402HL-741	100	5.45	1.00	740	7.00E-04	400
0402HL-821	200	5.85	0.220	820	7.00E-04	500

